Tool Make & Model

ACCRETECH / TSK UF3000EX-f

Tool Configuration / Specifications

UF3000ex series Prober Configuration

1.Configuration
Model: UF3000ex-f
Vintage: 2013
Auto loader , Double Load Port
√
GPIB interface √
Self-calibration system √
Auto Needle Alignment √
Auto Needle Height √
Auto pad alignment unit √
LCD Display (15 in) √
Real Time wafer map display
√
Multi-site probing function 3-64 dies
√
Needle Cleaning √
Probe Card Holder, RTGR-48
√
Chuck Type :Nickal12 inch
√
Offline ink function √
Ink check function √
Inker device (OPTIONAL）
√
Needle Inspection √
Profiler Sensor √
Configuration data √

2.PROBER SPECIFICATIONS
1. Power source:
Voltage：AC 220±20V
Consumption： Approximately 3kVA
2. Overall Size：1487W x 1622mm x 967H mm
3. Weight：1650kg (Standard)
4. Mechanical I/F with tester：Rectangular Prober card (cable end type)

Total Accuracy：±2μm
Chuck Temp: 50~150℃
7. Acceptable wafer dimensions
wafer diameter：Diameter of5",6",8"and12"
thickness：200-1000um
thickness variation：Less than ±50um
8. Max tested die numbers:UF3000EX : 250K DIES
9. Air supply
（1）Pressure：0.4 MPa or more
10. Vacuum supply：Less than 50kPa, 30 liters/minute
11. X/Y axes
Probing area：±170mm
Max Speed：500mm/s
Resolution：0.5um
12. Z axis
Full stroke：37mm
Max Speed：30mm/sec
Resolution：3.75um
13. Chuck Z control
Control accuracy：±2um
Overtravel：0~500um
0axis Rotation Range：±4°
Resolution：0.00028°
Fine Alignment：CCD ITV Image Processing
14. Hard Disk Drive
Capacity:40G byte or more
Number of drive:1drive
15. Floppy Disk Drive
Disk nominal size:3.5 inches
Number of drive:1drive
16. USB interface: use of external memory possible 17. Display: 15 inch TFT high color LCD

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